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611 **Cost Minimization for ASIC Hybrid BIST Designs**
I. Popa, A. Zafiu, and D. Cazacu
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617 **Si_3N_4 Based Non-Volatile Memory Structures with Embedded Si and Ge Nanocrystals**
Zs. J. Horváth, P. Basa, T. Jászi, A. E. Pap, G. Molnár, A. Kovalev, D. Wainstein, and P. Turmezei
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621 **Electrically Conductive Adhesives Modified with $AgNO_3$**
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625 **Vapor-Liquid-Solid Growth o ZnO Nanostructure**
J. Podzemský, and W. Schade
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629 **Electrodes Modified by Carbon Nanotubes for Pressure Measuring**
J. Pekárek, R. Ficek, R. Vrba, and M. Magát
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634 **Integrated Devices Based on Superprism Effect in Two-Dimensional Photonic Crystals**
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638 **Influence of Eu-doping on Wettability of TiO_2 Thin Films**
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643 **Flow Sensor for Microfluidic Applications – Based on Standard PWB Technology**
F. Ender, H. Sántha, and V. Székely
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649 **The Principle of a New Thermometer in HF CVD Reactor**
M. Kadlečíková, M. Kolmačka, F. Lazišťan, K. Jesenák, K. Pastorková, J. Breza, and D. Ďuračková
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J. Chomoucká, J. Drbohlavová, V. Adam, R. Kizek, and J. Hubálek
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658 **Electrical and Optical Properties of Ingaassb/GaSb**
B. Pődör, Zs. J. Horváth, and V. Rakovics
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662 **Defect Thermal Ionization Energies in Cu-III-VI2 Compound Semiconductors**
B. Pődör
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666 **Study of Nanosilver Filled Conductive Adhesives and Pastes for Electronics Packaging**
O. Telychkina, B. Boehme, M. Heimann, J. E. Morris, and K.-J. Wolter
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R. S. Yordanov
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G. Chindris, and H. Hedesiu
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M. Molhanec
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686 **Virtual Enterprise Network**
M. Januska, and M. Chodur
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J. Urbančík, and A. Pietriková
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I. Szendiuch, E. Hejatkova, M. Bursik, and M. Reznicek
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707 **Device and Technology of Wagon Bogie Y25Lsd Testing**
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713 **Application of Wavelet Trnasform to Train Spring System Diagnostics**
G. D. Geshev, E. N. Dimitrov, and N. G. Nenov
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N. L. Taranukha, Yu. P. Demakov, and V. P. Taranukha
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